

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the Application of Rule 53(b) Divisional:  
**MORIIZUMI, Kiyokazu et al.**

Group Art Unit: **1775 (Parent)**

Serial No.: **09/705,897 (Parent)**

Examiner: **C. LAM (Parent)**

Filed: **February 18, 2004**

Confirmation No.: **7597 (Parent)**

For: **MOUNTED CIRCUIT SUBSTRATE AND METHOD FOR  
FABRICATING THE SAME FOR SURFACE LAYER  
PADS THAT CAN WITHSTAND PAD EROSION BY  
MOLTEN SOLDER APPLIED OVER A PLURALITY OF  
TIMES**

Attorney Docket No.: 001480A  
Customer Number: 38834

**PRELIMINARY AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

February 24, 2004

Sir:

Prior to calculation of the filing fee and examination of this application, please amend  
the above-identified application as follows:

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page  
3 of this paper.

**Remarks/Arguments** begin on page 6 of this paper